

1. An adhesive material, for connecting a protuberant electrode of an electronic to a terminal electrode of a circuit board for carrying said electronic component, the adhesive material containing at least one curable resin and inorganic particles, wherein as to the inorganic particles, their specific surface area S (m^2/g) satisfies Equation (1) below, their mean particle size D_1 (μm) and maximum particle size D_2 (μ) respectively satisfy Equations (2) and (3) below,

$$3 < S \leq 17 \quad (1)$$

$$D_1 \leq 5 \quad (2)$$

$$D_2 \leq 0.5 (h_1 + h_2) \quad (3)$$

(wherein h_1 represents the height of the protuberant electrode in the electronic component, and h_2 represents the height of the terminal electrode in the circuit board),

and the content of said inorganic particles is 10 to 60 vol %.

2. The adhesive material according to Claim 1, wherein the mean particle size D_1 of the inorganic particles further satisfies the Equation (4) below.

$$0.1(h_1 + h_2) \geq D_1 \quad (4)$$

3. The adhesive material according to Claim 1, wherein said at least one curable resin is a thermosetting resin which exhibits a viscosity of 500 cps or less at 100°C.

4. The adhesive material according to any of Claim 1, further containing conductive particles having a mean particle size of 0.5 to 8.0 μm .

5. The adhesive material according to any of Claim 1, wherein the coefficient of moisture absorption in a 85% RH, 85°C atmosphere is 1.5 wt % or less.

6. The adhesive material according to any of Claim 1, wherein the electronic component is a semiconductor element.